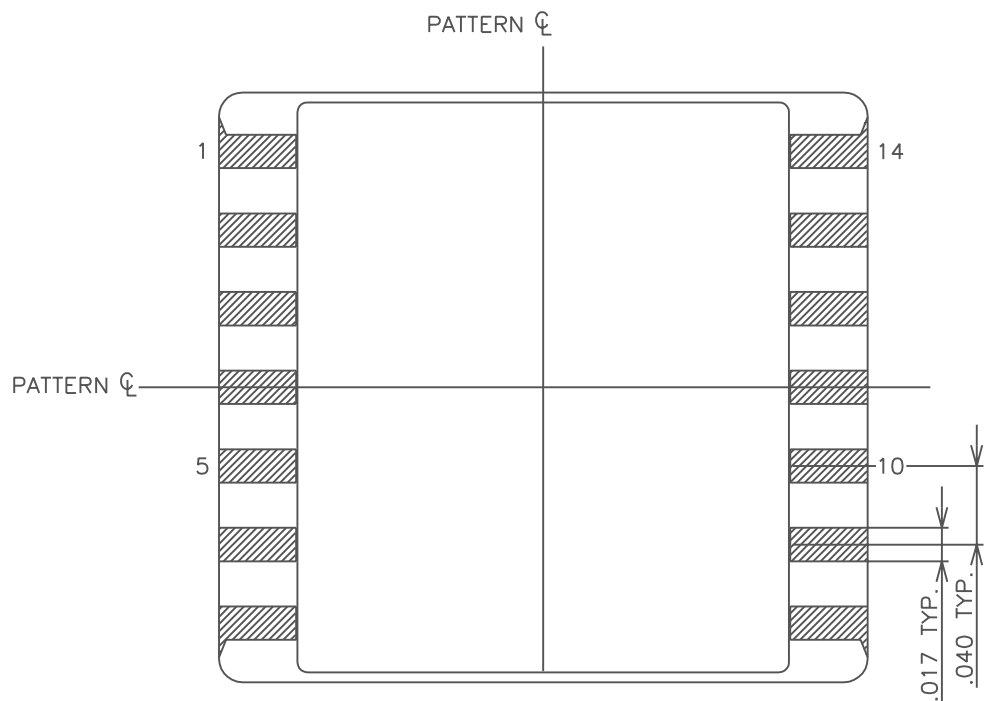


- NOTES.
1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
  2. SEAL AREA TO BE METALLIZED.
  3. DIE ATTACH AREA TO BE METALLIZED.
  4. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

MODIFICATION		NAME 14 LEAD FLAT PACKAGE				TOLERANCE UNLESS OTHERWISE SPECIFIED ±.005		DRAWN M.S		CHECKED S.T		APPROVED K.K/M.K		DATE FEB 21 89	
SCALE 8/1		MATERIAL AS INDICATED				THIRD ANGLE PROJECTION		DRAWING NO. KD-F89159-B		SHEET 1/2					
REDRAWN : CONVERTED CAD DATA. ADDED : SHEET 2/2		MAY 10 '01		T.S./H.K		S.H.K/S.N.I		H.S.A		KYOCERA		KYOCERA CORPORATION		KYOTO JAPAN	
CHANGED		DATE		DRAWN		CHECKED		APPROVED							





BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						14 LEAD FLAT PACKAGE	UNLESS OTHERWISE SPECIFIED	M.S	S.T	K.K/M.K	FEB.21.'89
						SCALE 15/1	MATERIAL				
							THIRD ANGLE PROJECTION				
	ADDED : THIS SHEET.	MAY.10.'01	T.S/H.K	SH.K/S.NI	H.SA		KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.		KD-F89159-B	SHEET 2/2
	CHANGED	DATE	DRAWN	CHECKED	APPROVED						

